

AMENDMENTS

IN THE SPECIFICATION

Please amend paragraph 30 as follows:

[0001] In the context of embodiments of the present invention, the expression “covering layer” will be used to refer to the totality of the layers on the diamond layer adapted to be directly attached to a thermal interface material. For example, the covering layer for the embodiment of Fig. 4 would encompass the final layer 15, the polished layer of metal 5 (including any number of metal layers based on application needs), and the adhesion layer 6. In turn, in the embodiment of Fig. 3, the covering layer would encompass the layer of metal 5 and the adhesion layer 6. Regarding Fig. 5, the covering layer would encompass the polished layer of metal 5, the barrier layer 18, and the adhesion layer 6. An embodiment of the present invention contemplates the provision of as few layers as possible on the upper surface 3. The thickness of all of the layers combined into the covering layer, including the layers in the layer of metal 5, may, according to embodiments of the present invention, be such that the covering layer is thicker than the roughness of the upper diamond surface being covered. The covering layer may thus be thick enough to fill in the roughness of the diamond surface and thick enough to be polished flat, as readily recognizable by one skilled in the art. As clearly seen in Figs. 3-6c, for example, the thermal coupling surface of the covering layer is substantially flat.